

Dear customer

ROHM Co., Ltd. ("ROHM"), on the 1st day of April, 2024, has absorbed into merger with 100%-owned subsidiary of LAPIS Technology Co., Ltd.

Therefore, all references to "LAPIS Technology Co., Ltd.", "LAPIS Technology" and/or "LAPIS" in this document shall be replaced with "ROHM Co., Ltd." Furthermore, there are no changes to the documents relating to our products other than the company name, the company trademark, logo, etc.

Thank you for your understanding.

ROHM Co., Ltd. April 1, 2024



# **ML86112 Evaluation Board User's Manual**

CVBS - MIPI CSI2 / LVTTL conversion LSI

#### General Description

This User's Manual describes the evaluation board(MLEB8360) of the display controller ML86112 for conversion analog video signal(NTSC,PAL) to MIPI-CSI2 or LVTTL. camera.

#### Specification

Name	MLEB8360		
Mounted device	ML86112		
Input power	12V DC		
Dimenseion	$(W)133mm \times (D)133mm \times (H)18mm$ Including connector and switch		
	Board dimension 120mm × 120mm t=1.6mm		
	•MLEB8360 is evaluation for ML86112 function.		
Features	<ul> <li>This board includes analog input and digital output connectors.</li> </ul>		
	•This board includes mini USB Type-B connector for control via PC.		



MLEB8360 Evaluation Board



#### Power and switch



Item	Name	Function	Description
CN1	DC12V	Power input connector	Connect DC12V. The port supplyes power for evaluation board.
CN15	INVCN	Power output connector	The port outputs CN1 power(DC12V). The port is available power for peripheral items for evaluation.
CN18	—	USBport	Connect USB port of PC. Control ML86112 by I2C communication.
SW1	—	Power switch	MLEB8360 power switch.
SW2	RESET	Reset switch	All devices reset when the switch is pressed.
SW3	_	SAS control switch	Control ML86112 slave address. OFF =82h / ON =80h
SW4	_	MTPWDN control switch	Control MTPWDN pin. Up : "L" input Down:"H" input
SW5		MTSTP control switch	Control MTSTP pin Up : "L" input Down:"H" input



Input



#### Output

CN2				
12226-5150-00FR				
(SDR	,26pins 3M Co	,Right- mpany	angle)	
Functions	Pin	Pin	Functions	
NC	1	2	MTD0P	
NC	3	4	MTCKP	
NC	5	6	NC	
NC	7	8	NC	
NC	9	10	NC	
NC	11	12	NC	
DGND	13	14	DGND	
MTD0N	15	16	NC	
MTCKN	17	18	NC	
NC	19	20	NC	
NC	21	22	NC	
NC	23	24	NC	
NC	25	26	NC	

PCB parts side



r				
CN3				
	XG4A	-2631		
(Connecto	or,26pin	s_strai	ght-heade)	
0	MRON C	Corporation	on	
Functions	Pin	Pin	Functions	
DGND	1	2	NC	
DGND	3	4	NC	
DGND	5	6	NC	
DGND	7	8	DCLK	
DGND	9	10	NC	
DGND	11	12	DY7	
DGND	13	14	DY6	
DGND	15	16	DY5	
DGND	17	18	DY4	
DGND	19	20	DY3	
DGND	21	22	DY2	
DGND	23	24	DY1	
DGND	25	26	DY0	

1		1
1	00	2
	00	
	00	
	00	
	00	
	00	
	00	
	00	
	00	
	00	
	00	
	00	
	00	
25		26

Pin diagram

	CN7		
	XF2M-3015-1A		
	(FFC_30pin)		
OMRON Corporation			
30	NC		
29	NC		
28	NC		
27	NC		
26	DGND		
25	NC		
24	NC		
23	DGND		
22	DCLK		
21	DGND		
20	NC		
19	NC		
18	NC		
17	NC		
16	DGND		
15	NC		
14	NC		
13	NC		
12	NC		
11	DGND		
10	DY7		
9	DY6		
8	DY5		
7	DY4		
6	DGND		
5	DY3		
4	DY2		
3	DY1		
2	DY0		
1	DGND		

CN8			
XF2M-4015-1A			
(FFC_40pin)			
C	OMRON Corporation		
40	NC		
39	NC		
38	NC		
37	NC		
36	NC		
35	DGND		
34	MTD0N		
33	MTD0P		
32	DGND		
31	NC		
30	NC		
29	DGND		
28	MTCKN		
27	MTCKP		
26	DGND		
25	NC		
24	NC		
23	DGND		
22	NC		
21	NC		
20	DGND		
19	NC		
18	NC		
17	DGND		
16	NC		
15	NC		
14	DGND		
13	NC		
12	NC		
11	DGND		
10	NC		
9	NC		
8	DGND		
7	NC		
6	NC		
5	DGND		
4	NC		
3	NC		
2	NC		
1	NC		



PCB side



## ■ Jumper pin settings

Item	Default	Function
ID 1	2.2 short	1-2pin short: Analog input VIN3,VIN4 setting
JP1	2-5 short	2-3pin short: Analog input VIN1,VIN2 setting
102	2.2 short	1-2pin short: Differential (+) input
JFZ	2-3 \$11011	2-3pin short: Single VIN1 input
1D2	2.2 short	1-2pin short: Differential (-) input
JES	2-5 short	2-3pin short: Single VIN2 input
JP4	Short	Single VIN1 connection
105	2.2 short	1-2pin short: Differential (+) input
JF J	2-3 \$11011	2-3pin short: Single VIN3 input
ID6	2.2 short	1-2pin short: Differential (-) input
JFO	2-3 \$11011	2-3pin short: Single VIN4 input
JP7	Open	Single VIN3 connection
JP8	Short	Power supply for digital core(1.2V) DVDD_C
JP9	Short	Power supply for digital IO (3.3V) DVDD_IO
JP10	Short	Power supply for MIPI-Tx(1.2V) DVDD_MT
JP11	Short	Power supply for analog(3.3V) AVDD
JP12	Short	Power supply for PLL(1.2V) PVDD
JP13	Short	Connect AGND and DGND
JP14	Short	Generate DC+5V from DC+12V
JP15	Short	Generate DC+3.3V from DC+5V
JP16	Short	Connect PGND and DGND
JP17	Open	-
JP18	Short	SDA
JP19	Short	SCL
JP20	Short	RSTN signal
1021	1.0 -1	MTPWDN/DY0 signal
JP21	1-2 short	Short 2-3 pin when LVTTLoutput
шээ	1.2 short	MTSTP/DY1 signal
JF 22	1-2 SHOIT	Short 2-3 pin when LVTTLoutput
JP23	Open	Single VIN2 connection
JP24	Open	Single VIN4 connection
JP25	Short	Power supply +5V
JP26	Short	Power supply +3.3V

### Monitor pin

Item	Monitor signal
TP1	STATUS
TP2	DCLK
TP3,TP4	AGND
TP5,TP6,TP7,TP8	DGND
TP9,TP10,TP11,TP12	NC

#### Analog video input

MLEB8630 can evaluate analog input (1) single end input (2) pseudo differential input (3) differential input as ML86112analog input format

Refer datasheet(PJDL86112) for register settings.

#### (1) single end input

ML86112		Competing
Name	No.	Connection
VIN1	31	Short JP1 2-3 pin Short JP4 Open JP23 Input analog video singal via VIN connector
VIN2	32	Short JP1 2-3 pin Open JP4 Short JP23 Input analog video singal via VIN connector
VIN3	1	Short JP1 1-2 pin Short JP7 Open JP24 Input analog video singal via VIN connector
VIN4	2	Short JP1 1-2 pin Open JP7 Short JP24 Input analog video singal via VIN connector



Allocation of jumper pin

#### (2) Pseudo differential input

ML86112		Composition
Name	No.	Connection
VIN1	31	Connect 750hm between JP2-2pin and JP3-2pin Connect analog video signal(+) to JP2-2pin
VIN2	32	Connect analog video signal(-) to JP3-2pin

ML86112		Connection
Name	No.	Connection
VIN3	1	Connect 750hm between JP5-2pin and JP6-2pin Connect analog video signal(+) to JP5-2pin
VIN4	2	Connect analog video signal(-) to JP6-2pin



Connection for Pseudo differential video signal input to VIN1-VIN2

#### (3) Differential input

ML86112		Composition	
Name	No.	Connection	
VIN1	31	Short JP2 1-2pin Reject R5 Connect analog video signal(+) to JP2-2pin	
VIN2	32	Short JP3 1-2pin Reject R3 Connect analog video signal(-) to JP3-2pin	

ML86112		Composition		
Name	No.			
VIN3	1	Short JP5 1-2pin Reject R11 Connect analog video signal(+) to JP2-2pin		
VIN4	2	Short JP6 1-2pin Reject R12 Connect analog video signal(-) to JP3-2pin		



Connection for differential video signal input to VIN1-VIN2

### ■ Video Arrangement Studio2

#### •Main window

Video Arrangement St	tudio2	Open	GUI for ml8	86112	7 <u>1</u> 71	□ ×	
File View Command	Help SE DEC	NC NR OTH TBL		Page +			
Select Devices © Video Decoder C Video Encoder C NR FIFO	80 h 88 h 88 h	m186112 Select no dev Select no dev	ice	2C Slave Address bit 6bit 5bit 4bit 3bit 8 C C C C	: 2bit 1bit 0bit C C 0 80	h	
C Other	00 h	Select no dev	ice 🗾 Sel	ect ml86112	Select slav	ve addres	s 80h or 82h
Direct Control Control Register Sub address Wr: 00 h Res Control Register 00 h Res Result	r itten val ad value 00 h address	Write Read	Byte size Sub address C 1 byte C 2 bytes Value C 1 byte C 2 bytes	-Communication Pe TEST	ozt Test	_	
< Ready			Can rea	d and write val	lue of specified	l sub add	ress

#### •Port parameter setting

#### File $\rightarrow$ Set Port Parameters

Select Communication Dialog	23				
Select I2C Protocol	ок				
I2cDockBoard	Cancel				
Select I2cDockBoard					

Set Port Paramet			
COM port	COM1 -	OK	
Baud Rate	38400 💌	Cancel	
Data Bits	8 💌		
Parity	No Parity 💌	Select Boud R	ate 38400
Stop Bits	1		
Flow Control	No Control 💌		
Timeout	2000	[msec]	

#### [Notes in Use]

The analog input section of ML86112 is developed based on the standard video signal. We have improved it to obtain a stable behavior for nonstandard video signals as well. However, a stable behavior for every signal is not guaranteed, since there are various situations in the signal condition and usage environment such as airwave signals received in light electric field areas, VTR playback signals, video signals with switching signal sources, noise contamination signals, and simplified video signals of various cameras and game machines. Please thoroughly evaluate and examine the product in assumed signal conditions and usage environments before you adopt it.

### Revision history

	Issue Date	Page		
Document No.		Previous Edition	New Edition	Description
FEBL86112-01	2020.08.03		13	First edition issued
FEBL86112-02	2024.03.13	13	13	No change
FEBL86112-03	2024.03.13	13	13	P13: Updated "Notice"

#### Notes

1) When using LAPIS Technology Products, refer to the latest product information and ensure that usage conditions (absolute maximum ratings<sup>\*1</sup>, recommended operating conditions, etc.) are within the ranges specified. LAPIS Technology disclaims any and all liability for any malfunctions, failure or accident arising out of or in connection with the use of LAPIS Technology Products outside of such usage conditions specified ranges, or without observing precautions. Even if it is used within such usage conditions specified ranges, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury, fire or the other damage from break down or malfunction of LAPIS Technology Products, please take safety at your own risk measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures.

\*1: Absolute maximum ratings: a limit value that must not be exceeded even momentarily.

- 2) The Products specified in this document are not designed to be radiation tolerant.
- 3) Descriptions of circuits, software and other related information in this document are provided only to illustrate the standard operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. And the peripheral conditions must be taken into account when designing circuits for mass production. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, and other related information.
- 4) No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of LAPIS Technology or any third party with respect to LAPIS Technology Products or the information contained in this document (including but not limited to, the Product data, drawings, charts, programs, algorithms, and application examples, etc.). Therefore, LAPIS Technology shall have no responsibility whatsoever for any dispute, concerning such rights owned by third parties, arising out of the use of such technical information.
- 5) LAPIS Technology intends our Products to be used in a way indicated in this document. Please be sure to contact a ROHM sales office if you consider the use of our Products in different way from original use indicated in this document. For use of our Products in medical systems, please be sure to contact a LAPIS Technology representative and must obtain written agreement. Do not use our Products in applications which may directly cause injuries to human life, and which require extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters, etc. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising by using the Product for purposes not intended by us without our prior written consent.
- 6) All information contained in this document is subject to change for the purpose of improvement, etc. without any prior notice. Before purchasing or using LAPIS Technology Products, please confirm the latest information with a ROHM sales office. LAPIS Technology has used reasonable care to ensure the accuracy of the information contained in this document, however, LAPIS Technology shall have no responsibility for any damages, expenses or losses arising from inaccuracy or errors of such information.
- Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. LAPIS Technology shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
- 8) When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.
- Please contact a ROHM sales office if you have any questions regarding the information contained in this document or LAPIS Technology's Products.
- 10) This document, in part or in whole, may not be reprinted or reproduced without prior consent of LAPIS Technology.

(Note) "LAPIS Technology" as used in this document means LAPIS Technology Co., Ltd.

Copyright 2020 - 2024 LAPIS Technology Co., Ltd.

https://www.lapis-tech.com/en/

LTSZ08023 • 01 • 002